

LTM4611 133LD 15mm X 15mm X 4.32mm (TABLE OF MATERIAL DECLARATION)							
The LTM4611 is RoHS compliant per EU RoHS Directive 2003/95/EC.							
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)							
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2265	Barium Compounds	7727-43-7	0.00372	1.6400
				Bismaleimide/Triazine Resin/Filter Substances(Silica Crytaline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2	0.08991	39.6900
				Copper Metal	7440-50-8	0.04778	21.0900
				Copper Compounds	147-14-8	0.00003	0.0140
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.0030
				Gold metal or alloy	7440-57-5	0.00082	0.3600
				Nickel	7440-02-0	0.00526	2.3200
				Zinc	7440-66-6	0.00007	0.0290
				Bisphenol A epoxyresin	25068-38-6	0.00001	0.0050
				Continuos Filament Fiber Glass	65997-17-3	0.07064	31.1800
				Acrylic Resin	non-disclosure	0.00709	3.1300
				Epoxy Resin	non-disclosure	0.00011	0.0470
				Silica amorphous	7631-86-9	0.00005	0.0200
				Talc;not containing fibers like asbestos	14807-96-9	0.00043	0.1900
				Aromatic Carbonyl compounds	non-disclosure	0.00041	0.1800
				Cyanoguanidine	461-58-5	0.00001	0.0050
				Amine compounds	non-disclosure	0.00005	0.0230
				Leveling agent and others	non-disclosure	0.00016	0.0720
				Imidazole system curingg reagent	non-disclosure	0.00001	0.0050
2	Solder Paste	Alloy	0.0130	Sn	7440-31-5	0.01239	95.0000
				Sb	7440-36-0	0.00065	5.0000
3	Passive/Active Components		0.8909	Iron Powder (Fe)	7439-89-6	0.65576	73.6036
				Copper (Cu)	7440-50-8	0.17826	20.0075
				Nickel (Ni)	7440-02-0	0.00682	0.7656
				Tin (Sn)	7440-31-5	0.00682	0.7654
				Ceramic (Ba) Compounds	12047-27-7	0.04324	4.8533
4	Active Ics	Silicon	0.0132	Silicon	7440-21-3	0.01324	100.0000
5	Wire	Gold	0.0023	Au	7440-57-5	0.00230	99.9900
6	Encapsulation	Epoxy Resin	1.4769	Fused Silica	60676-86-0	1.14016	77.2000
				Epoxy Resin	non-disclosure	0.13144	8.9000
				Phenol Resin	non-disclosure	0.13144	8.9000
				Crytalline Silica	14808-60-7	0.04431	3.0000
				Carbon Black	1333-86-4	0.00738	0.5000
				Metal Hydroxide	non-disclosure	0.02215	1.5000
				Total Package Weight			2.6229

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts

2.62292